

9001 V3.0, V3.1, and V3.5 Liquid Encapsulants

Introduction

Version 3.0, 3.1, and 3.5 are upgrades of the flexible "instant curing" Dymax 9001 encapsulant. Environmental testing and reliability data are listed below.

Procedure and Materials

One hundred (100), one hundred and eighty (180), and five hundred (500) mil dies bonded to FR-4 circuit boards with

1 mil gold wire were encapsulated under approximately 30 mils of Dymax 9001-V3.0 resin. Cures were accomplished on a UVC-6PT curing unit with the conveyor belt set at 2 feet per minute (30 seconds of curing time). The measured UV intensity at 365 nm was 150 mW/cm².

Thermal Cycling

Ten encapsulated chips were placed in a thermal cycling oven set to cycle between -40°C and +125°C with a thirty-minute dwell at each temperature and a ninety minute transition time between temperatures. After ten cycles and equilibration at room temperature for one hour, each wire was tested for conductivity. A 50% change in resistance was deemed a failure.

Thermal Cycle Range	Number of Cycles	Result
-40°C to +125°C	2,000	Pass

Autoclave Resistance at 120°C, 30 psi

Ten encapsulated chips were suspended two inches above the surface of tap water in an autoclave at 30 lbs of pressure. Temperature was measured at 120°C. The chips were allowed to equilibrate for one hour at room temperature before testing.

Hours	Failures
300	0%
500	0%
1,000	0%

Humidity Resistance at 85°C and 100% R.H.

Ten encapsulated chips were suspended one inch above the surface of the water in a sealed glass container. The container was placed in an isothermal oven and maintained at 85°C. The conductivity of each wire was tested after equilibrating at room temperature for thirty minutes.

Hours	Failures
500	0%
800	0%
1,000	0%



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